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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

### Details

Product StatusActiveCore ProcessorH8/300HCore Size16-BitSpeed25MHzConnectivitySCI, SmartCardPeripheralsDMA, PWM, WDTNumber of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-Nufage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOgerating Temperature4.0°C ~ 85°C (TA)Mounting Type10-TCFPSupplier Device Package-Purchase URLhttps://www.exfl.com/product-detail/renesa-electronics-america/df3069rx25sw		
Core Size16-BitSpeed25MHzConnectivitySCI, SmartCardPeripheralsDMA, PWM, WDTNumber of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature4.0°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Product Status	Active
Speed25MHzConnectivitySCI, SmartCardPeripheralsDMA, PWM, WDTNumber of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFP	Core Processor	H8/300H
ConnectivitySCI, SmartCardPeripheralsDMA, PWM, WDTNumber of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFP	Core Size	16-Bit
PeripheralsDMA, PWM, WDTNumber of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFP	Speed	25MHz
Number of I/O70Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Connectivity	SCI, SmartCard
Program Memory Size512KB (512K x 8)Program Memory TypeFLASHEEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Peripherals	DMA, PWM, WDT
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EEPROM Size-RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Program Memory Size	512KB (512K x 8)
RAM Size16K x 8Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Program Memory Type	FLASH
Voltage - Supply (Vcc/Vdd)4.5V ~ 5.5VData ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	EEPROM Size	-
Data ConvertersA/D 8x10b; D/A 2x8bOscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	RAM Size	16K × 8
Oscillator TypeInternalOperating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Operating Temperature-40°C ~ 85°C (TA)Mounting TypeSurface MountPackage / Case100-TQFPSupplier Device Package-	Data Converters	A/D 8x10b; D/A 2x8b
Mounting Type     Surface Mount       Package / Case     100-TQFP       Supplier Device Package     -	Oscillator Type	Internal
Package / Case 100-TQFP Supplier Device Package -	Operating Temperature	-40°C ~ 85°C (TA)
Supplier Device Package -	Mounting Type	Surface Mount
	Package / Case	100-TQFP
Purchase URL https://www.e-xfl.com/product-detail/renesas-electronics-america/df3069rx25wv	Supplier Device Package	-
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General register ER7 has the function of stack pointer (SP) in addition to its general-register function, and is used implicitly in exception handling and subroutine calls. Figure 2.5 shows the stack.

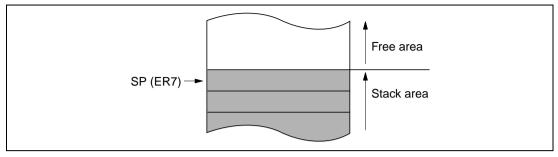


Figure 2.5 Stack

## 2.4.3 Control Registers

The control registers are the 24-bit program counter (PC) and the 8-bit condition code register (CCR).

**Program Counter (PC):** This 24-bit counter indicates the address of the next instruction the CPU will execute. The length of all CPU instructions is 2 bytes (one word), so the least significant PC bit is ignored. When an instruction is fetched, the least significant PC bit is regarded as 0.

**Condition Code Register (CCR):** This 8-bit register contains internal CPU status information, including the interrupt mask bit (I) and half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags.

**Bit 7—Interrupt Mask Bit (I):** Masks interrupts other than NMI when set to 1. NMI is accepted regardless of the I bit setting. The I bit is set to 1 at the start of an exception-handling sequence.

**Bit 6—User Bit or Interrupt Mask Bit (UI):** Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions. This bit can also be used as an interrupt mask bit. For details see section 5, Interrupt Controller.

**Bit 5—Half-Carry Flag (H):** When the ADD.B, ADDX.B, SUB.B, SUBX.B, CMP.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise. When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

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If M (1 to 255) is the size of the block transferred at each request and N (1 to 65,536) is the number of blocks to be transferred, then ETCRAH and ETCRAL should initially be set to M and ETCRB should initially be set to N.

Figure 7.10 illustrates how block transfer mode operates. In this figure, bit TMS is cleared to 0, meaning the block area is the destination.

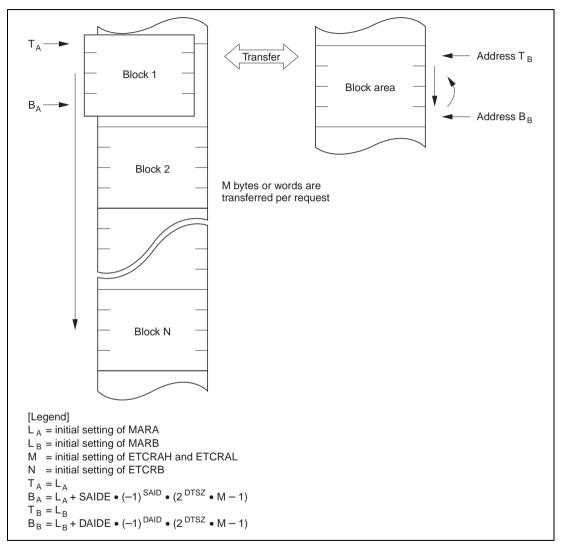


Figure 7.10 Operation in Block Transfer Mode

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Figure 7.16 shows the timing when the DMAC is activated by the falling edge of  $\overline{\text{DREQ}}$  in normal mode.

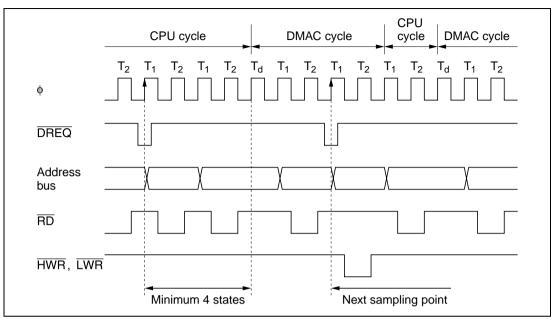


Figure 7.16 Timing of DMAC Activation by Falling Edge of DREQ in Normal Mode



# Table 8.24 Port B Pin Functions (Mode 7)

### Pin Pin Functions and Selection Method

PB <sub>7</sub> /TP <sub>15</sub> / RxD <sub>2</sub>	Bit RE in SCR of SCI2, bit SMIF in SCMR, bit NDER15 in NDERB, and bit PB,DDR select the pin function as follows.								
	SMIF		0				1		
	RE		0				—		
	PB,DDR	0	0 1 1			_	—		
	NDER15	_	0		1	_	—		
	Pin function	PB <sub>7</sub> input	PB <sub>7</sub> outp	out TP <sub>15</sub>	output I	RxD <sub>2</sub> input	RxD <sub>2</sub> input		
PB <sub>6</sub> /TP <sub>14</sub> / TxD <sub>2</sub>	Bit TE in SCR of SCI2, bit SMIF in SCMR, bit NDER14 in NDERB, and bit PB,DDR select the pin function as follows.								
	SMIF		0						
	TE		0						
	PB <sub>6</sub> DDR	0	1		1	_	_		
	NDER14	_	0		1	_	_		
				put TP <sub>14</sub> output TxI					
	Pin function Note: * Functions	PB <sub>6</sub> input as the TxD2 outpu	PB <sub>6</sub> outp	14		xD <sub>2</sub> output	TxD <sub>2</sub> output*		
	Note: * Functions	as the TxD2 outpune pin is at high-imp	t pin, but there bedance.	are two states	: one in whicl	n the pin is dr	iven, and anothe		
	Note: * Functions in which the Bit C/A in SMR of S	as the TxD2 outpune pin is at high-imp	t pin, but there bedance.	are two states	: one in whicl	n the pin is dr	iven, and anothe		
	Note: * Functions in which th Bit C/Ā in SMR of S function as follows.	as the TxD2 outpune pin is at high-imp	t pin, but there bedance. I CKE1 in SCR	are two states	: one in whicl	n the pin is dr	R select the pin		
PB <sub>s</sub> /TP <sub>13</sub> / SCK <sub>2</sub>	Note: * Functions in which th Bit C/Ā in SMR of S function as follows.	as the TxD2 outpune pin is at high-imp	t pin, but there bedance. I CKE1 in SCR	are two states , bit NDER13	: one in whicl	n the pin is dr	R select the pin		
	Note: * Functions in which th Bit C/Ā in SMR of S function as follows. CKE1 C/Ā	as the TxD2 outpune pin is at high-imp	t pin, but there bedance. I CKE1 in SCR	are two states , bit NDER13	n NDERB, an	n the pin is dr	R select the pin		
	Note: * Functions in which th Bit C/Ā in SMR of S function as follows. CKE1 C/Ā CKE0	as the TxD2 outpu ne pin is at high-imp Cl2, bits CKE0 and	t pin, but there bedance. I CKE1 in SCR	are two states	n NDERB, an	n the pin is dr	R select the pin		
	Note: * Functions in which the Bit C/Ā in SMR of S function as follows. CKE1 C/Ā CKE0 PB <sub>s</sub> DDR	as the TxD2 outpu ne pin is at high-imp Cl2, bits CKE0 and	t pin, but there bedance. I CKE1 in SCR	are two states	n NDERB, an	n the pin is dr	R select the pin		
SCK2	Note: * Functions in which th Bit C/Ā in SMR of S function as follows. CKE1 C/Ā CKE0 PB <sub>s</sub> DDR NDER13	as the TxD2 outpu ne pin is at high-imp Cl2, bits CKE0 and 0 0 PBs input	t pin, but there bedance. I CKE1 in SCR 0 1 0 PB <sub>s</sub> output	are two states a, bit NDER13 0 0 1 1 TP <sub>13</sub> output	n NDERB, an 1 	n the pin is dr	R select the pin 1		
SCK2	Note: * Functions in which ti Bit C/Ā in SMR of S function as follows. CKE1 C/Ā CKE0 PB,DDR NDER13 Pin function	as the TxD2 output ne pin is at high-imp CI2, bits CKE0 and 0 0 PB <sub>s</sub> input	t pin, but there bedance. I CKE1 in SCR 0 1 0 PB <sub>s</sub> output	are two states a, bit NDER13 0 0 1 1 TP <sub>13</sub> output n function as for	n NDERB, an 1 	n the pin is dr	R select the pin 1		
	Note: * Functions in which tl         Bit C/Ā in SMR of S function as follows.         CKE1         C/Ā         CKE0         PB₅DDR         NDER13         Pin function         Bit NDER12 in NDE	as the TxD2 output ne pin is at high-imp CI2, bits CKE0 and 0 0 PB <sub>s</sub> input	t pin, but there bedance. I CKE1 in SCR 0 1 0 PB <sub>s</sub> output R select the pir	are two states bit NDER13 0 0 1 1 TP <sub>13</sub> output n function as for	1 SCK <sub>2</sub> output	n the pin is dr	R select the pin 1 1		

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